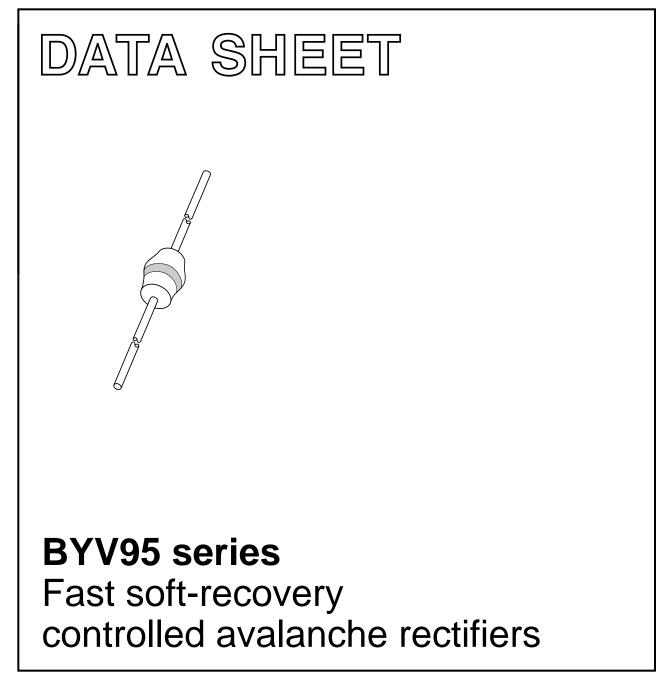
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of April 1982 File under Discrete Semiconductors, SC01 1996 Jun 07



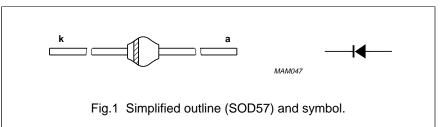
Philips Semiconductors

### FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- Available in ammo-pack.

#### DESCRIPTION

Rugged glass SOD57 package, using a high temperature alloyed construction. This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage				
	BYV95A		_	200	V
	BYV95B		_	400	V
	BYV95C		-	600	V
V <sub>R</sub>	continuous reverse voltage				
	BYV95A		_	200	V
	BYV95B		_	400	V
	BYV95C		-	600	V
I <sub>F(AV)</sub>	average forward current	$T_{tp}$ = 65 °C; lead length = 10 mm see Fig. 2; averaged over any 20 ms period; see also Fig. 6	_	1.5	A
		T <sub>amb</sub> = 65 °C; PCB mounting (see Fig.11); see Fig. 3; averaged over any 20 ms period; see also Fig. 6	_	0.8	A
I <sub>FRM</sub>	repetitive peak forward current	$T_{tp} = 65 \text{ °C}; \text{ see Fig. 4}$	_	17	A
		T <sub>amb</sub> = 65 °C; see Fig. 5	_	9	A
I <sub>FSM</sub>	non-repetitive peak forward current	t = 10 ms half sine wave; T <sub>j</sub> = T <sub>j max</sub> prior to surge; $V_R = V_{RRMmax}$	-	35	A
E <sub>RSM</sub>	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j max}$ prior to surge; inductive load switched off	_	10	mJ
T <sub>stg</sub>	storage temperature		-65	+175	°C
T <sub>i</sub>	junction temperature	see Fig. 7	-65	+175	°C

**BYV95** series

### **BYV95** series

### **ELECTRICAL CHARACTERISTICS**

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_F = 3 \text{ A}; T_j = T_{j \text{ max}}; \text{ see Fig. 8}$	_	_	1.35	V
		I <sub>F</sub> = 3 A; see Fig. 8	_	_	1.60	V
V <sub>(BR)R</sub>	reverse avalanche breakdown voltage	I <sub>R</sub> = 0.1 mA				
	BYV95A		300	_	-	V
	BYV95B		500	_	-	V
	BYV95C		700	_	-	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = V <sub>RRMmax</sub> ; see Fig. 9	-	-	1	μA
		$V_R = V_{RRMmax}$ ; $T_j = 165 \text{ °C}$ ; see Fig. 9	_	-	150	μA
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 0.5 A$ to $I_R = 1 A$ ; measured at $I_R = 0.25 A$ ; see Fig. 12	_	_	250	ns
C <sub>d</sub>	diode capacitance	$f = 1 \text{ MHz}; V_R = 0 \text{ V}; \text{ see Fig. 10}$	-	45	_	pF
$\frac{dI_R}{dt}$	maximum slope of reverse recovery current	when switched from $I_F$ = 1 A to $V_R \ge 30$ V and $dI_F/dt$ = –1 A/µs; see Fig.13	_	_	7	A/μs

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	46	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	100	K/W

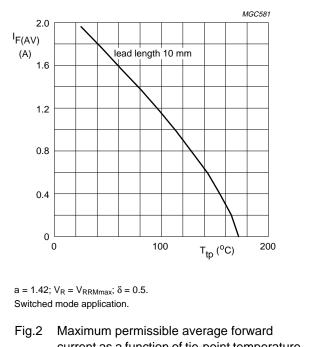
#### Note

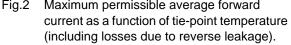
1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.11. For more information please refer to the *'General Part of Handbook SC01'*.

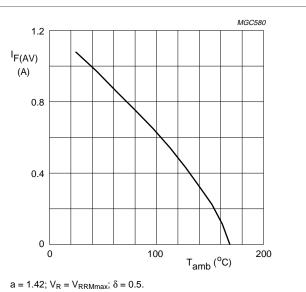
## BYV95 series

Product specification

### **GRAPHICAL DATA**







a = 1.42;  $v_R = v_{RRMmax}$ ; o = 0.5. Device mounted as shown in Fig.11. Switched mode application.

Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

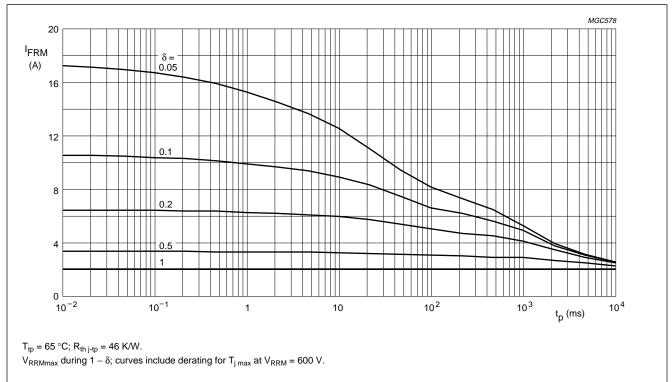
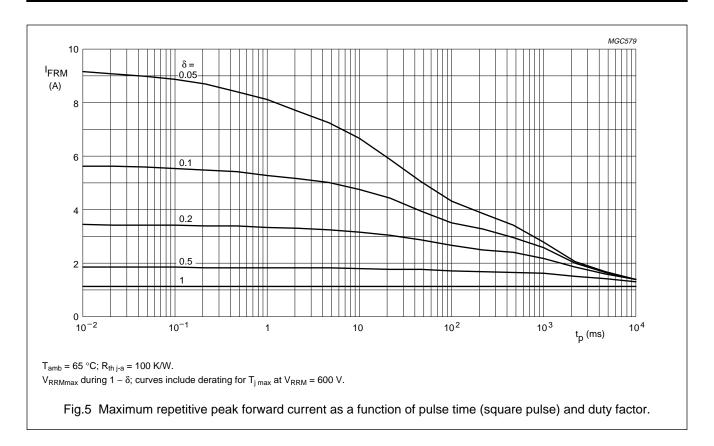
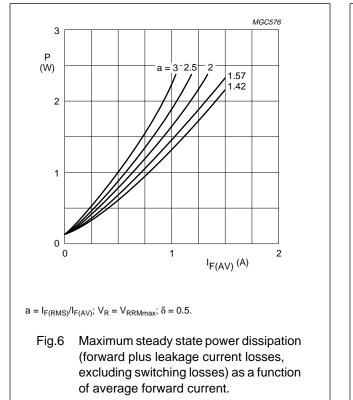
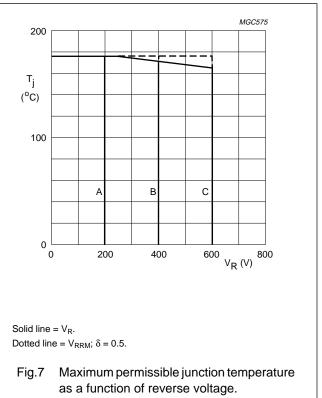


Fig.4 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

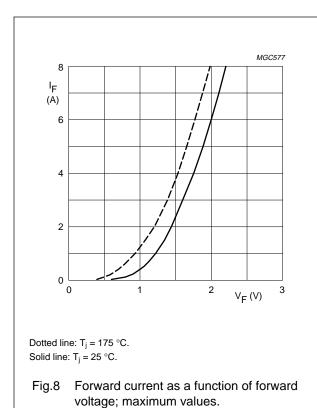
## **BYV95** series











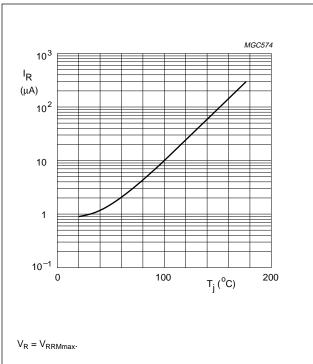
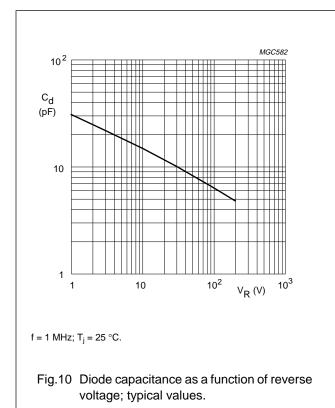
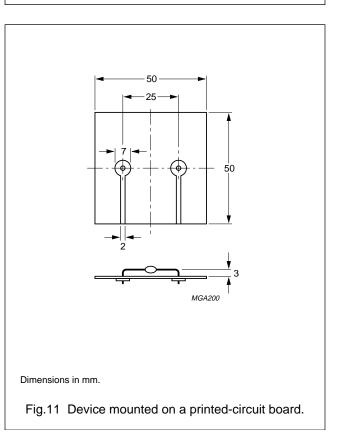
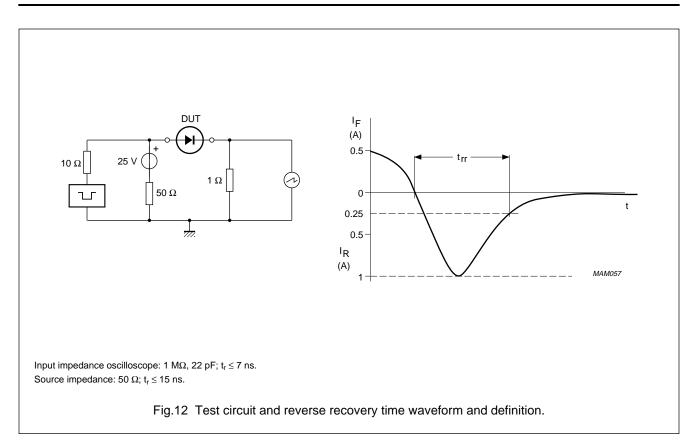


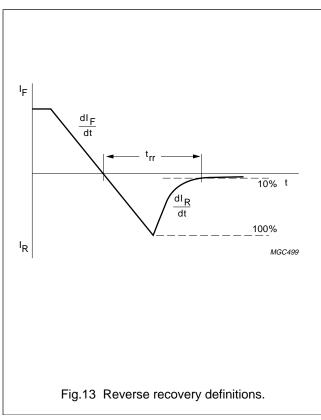
Fig.9 Reverse current as a function of junction temperature; maximum values.





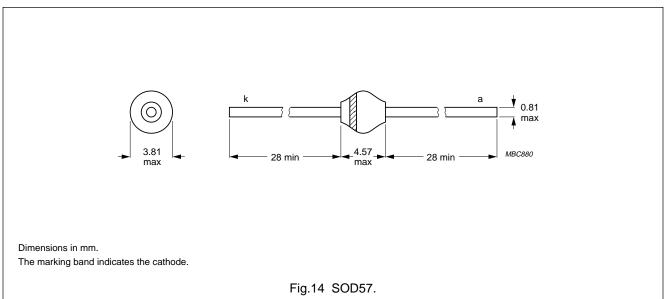
## **BYV95** series





## **BYV95** series

### PACKAGE OUTLINE



#### DEFINITIONS

Data Sheet Status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.		
Application information		
Where application information is given, it is advisory and does not form part of the specification.		

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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